

REPLACEMENT SHEET

Title: Integration of Annealing Capability Into Metal Deposition or CMP Tool

1st Named Inventor: Jick M. Yu

Application No.: 10/810,735

Docket No. 42P6934D



WAFERS HAVING
METAL LAYERS
DEPOSITED
THEREON

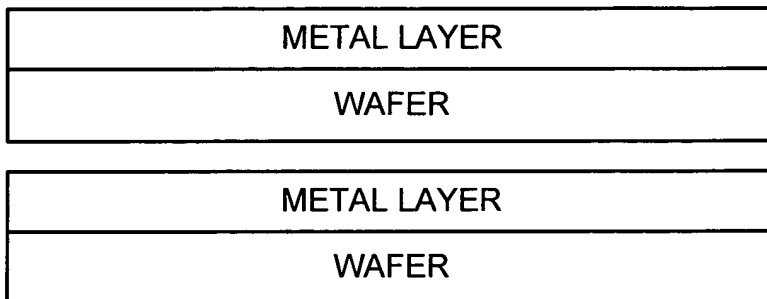
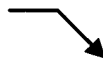


FIG. 7

WAFERS HAVING
METAL LAYERS
THAT HAVE BEEN
POLISHED

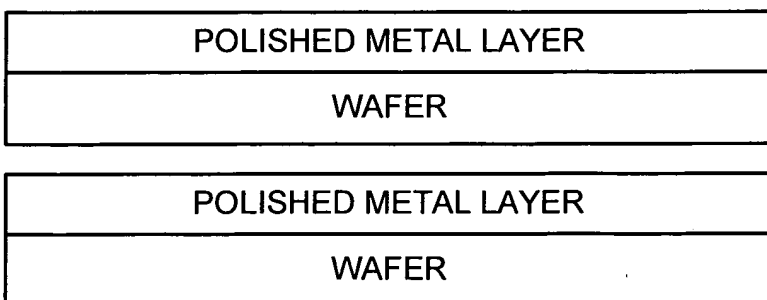
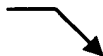


FIG. 8